Product Change Notification / NTDO-03WCVB135

Date:

06-May-2021

Product Category:

Bluetooth Silicon

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4657 Initial Notice: Implement MSL 1 for BM83SM1 device family available in 50L MODULE (32x15x2.5mm) package assembled at UMEC assembly site

Affected CPNs:

NTDO-03WCVB135_Affected_CPN_05062021.pdf
NTDO-03WCVB135_Affected_CPN_05062021.csv

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Implement MSL 1 for BM83SM1 device family available in 50L MODULE (32x15x2.5mm) package assembled at UMEC assembly site

Pre and Post Change Summary:

Details	PRE-CHANGE	POST CHANGE

Assembly site	UMEC	UMEC
MSL Level	MSL 3	MSL 1

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve productivity by upgrading to MSL 1.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: September 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	May 2021					**-->**	**September 2021**				
Workweek	19	20	21	22	23		36	37	38	39	40
Initial PCN Issue Date	X										
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change: Traceability code, MSL label

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:May 6, 2021 Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_NTDO-03WCVB135_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

QUALIFICATION PLAN SUMMARY

PCN # NTDO-03WCVB135

Date:
April 20, 2021

Implement MSL 1 for BM83SM1 device family in 50L MODULE (32x15x2.5mm) package assembled at UMEC assembly site

Purpose: Implement MSL 1 for BM83SM1 device family in 50L MODULE (32x15x2.5mm) package assembled at UMEC assembly site

Misc.	**Assembly site**	UMEC
	MP Code (MPC)	ZY0237XZXM01
	Part Number (CPN)	BM83SM1-00AA
	CCB	4657
Package	**Type**	50L MODULE
	Size	32x15x2.5 mm

Test Name	Conditions	Sample Size	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
High Temperature Storage Life (HTSL)	JESD22A-103. 150°C for 1008 hours. Readpoints at 0, 504, and 1008 hours. Electrical test pre and post stress at +25°C and hot temp.	8	3	24	0	50	MMT	MTAI	Spare should be properly identified.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. JESD22A113 MSL 1@260°C	24	3	72	0	15	MMT	MTAI	Spares should be properly identified.
Unbiased HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C.	8	3	24	0	10	MMT	MTAI	Spare should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased High Temperature/Humidity	+85°C/85% RH for 1000 hours. Readpoints at 0, 500, and 1000 hours. Electrical test pre and post stress at +25°C and/or hot temp.	8	3	24	0	50	MMT	MTAI	Spare should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22A104. -40°C to +125°C for 1000 cycles. Readpoints at 0, 500, and 1000 cycles. Electrical test pre and post stress at +25°C and/or hot temp.	8	3	24	0	30	MMT	MTAI	Spare should be properly identified. Use the parts which have gone through Pre-conditioning.

Affected Catalog Part Numbers (CPN)

BM83SM1-00AA
BM83SM1-00AB
BM83SM1-00TA